VC KVI-GSI-TUD technical meeting 21-12-2011

O. Kiselev, M. von Schmidt, M. Lindemulder, C. Rigollet, Th. Kroell, K. Yue, P. Schakel, N. Kalantar

1. The bonding of 2 chips on the front-end board built at KVI is done at GSI. The readout electronics for the tests of the board will be done at TUD. However the VME processor (for data acquisition) is not available at present. Peter Schakel will go to TUD to help with the tests when the setup is complete. Mirko should be in contact with Peter to let him know when he can travel to TUD.
2. Mechanical design and manufacturing:
	1. The machining of the big pocket is in progress and should be ready by the end of January 2012.
	2. Oleg is in contact with the Vacuum group about mounting and testing the moving mechanisms, this should happen towards the end of January 2012. The in-ring pocket and a spare will be ready by then.
	3. The 3 bellows have been ordered.
3. The next meeting is planned for the 11th January 2012 at 11:00.

Merry Christmas and a Happy new year to all!